

August 1998



National Semiconductor

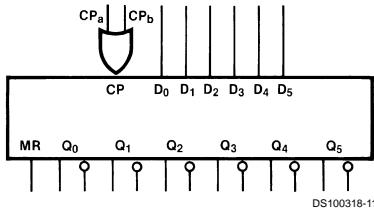
## 100351

### Low Power Hex D Flip-Flop

#### General Description

The 100351 contains six D-type edge-triggered, master/slave flip-flops with true and complement outputs, a pair of common Clock inputs ( $CP_a$  and  $CP_b$ ) and common Master Reset (MR) input. Data enters a master when both  $CP_a$  and  $CP_b$  are LOW and transfers to the slave when  $CP_a$  and  $CP_b$  (or both) go HIGH. The MR input overrides all other inputs and makes the Q outputs LOW. All inputs have 50 k $\Omega$  pull-down resistors.

#### Logic Symbol



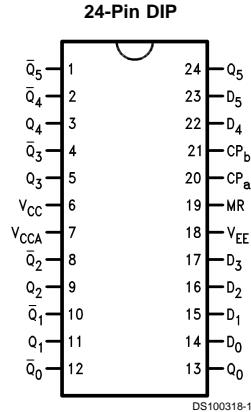
DS100318-11

#### Features

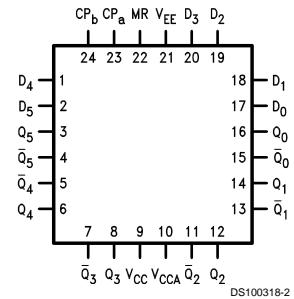
- 40% power reduction of the 100151
- 2000V ESD protection
- Pin/function compatible with 100151
- Voltage compensated operating range: -4.2V to -5.7V
- Standard Microcircuit Drawing (SMD) 5962-9457901

Pin Names	Description
D <sub>0</sub> -D <sub>5</sub>	Data Inputs
CP <sub>a</sub> , CP <sub>b</sub>	Common Clock Inputs
MR	Asynchronous Master Reset Input
Q <sub>0</sub> -Q <sub>5</sub>	Data Outputs
Q <sub>0</sub> -Q <sub>5</sub>	Complementary Data Outputs

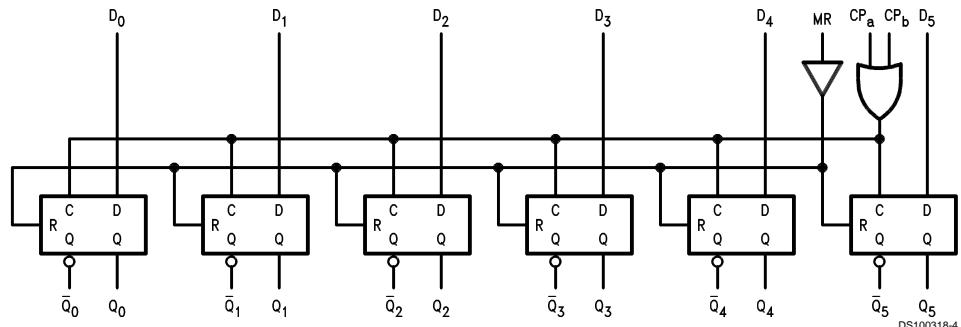
## Connection Diagrams



## 24-Pin Quad Cerpak



## Logic Diagram



## Truth Tables (Each Flip-flop)

### Synchronous Operation

Inputs				Outputs
D <sub>n</sub>	CP <sub>a</sub>	CP <sub>b</sub>	MR	Q <sub>n(t+1)</sub>
L	✓	L	L	L
H	✓	L	L	H
L	L	✓	L	L
H	L	✓	L	H
X	H	✓	L	Q <sub>n(t)</sub>
X	✓	H	L	Q <sub>n(t)</sub>
X	L	L	L	Q <sub>n(t)</sub>

### Asynchronous Operation

Inputs				Outputs
D <sub>n</sub>	CP <sub>a</sub>	CP <sub>b</sub>	MR	Q <sub>n(t+1)</sub>
X	X	X	H	L

H = HIGH Voltage Level

L = LOW Voltage Level

X = Don't Care

t = Time before CP positive transition

t+1 = Time after CP positive transition

✓ = LOW-to-HIGH transition

<b>Absolute Maximum Ratings</b> (Note 1)		ESD (Note 2)		$\geq 2000V$			
If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.							
Above which the useful life may be impaired							
Storage Temperature ( $T_{STG}$ )	-65°C to +150°C						
Maximum Junction Temperature ( $T_J$ )							
Ceramic	+175°C						
$V_{EE}$ Pin Potential to Ground Pin	-7.0V to +0.5V						
Input Voltage (DC)	$V_{EE}$ to +0.5V						
Output Current (DC Output HIGH)	-50 mA						
<b>Recommended Operating Conditions</b>							
Case Temperature ( $T_C$ )							
Military	-55°C to +125°C						
Supply Voltage ( $V_{EE}$ )	-5.7V to -4.2V						
<b>Note 1:</b> Absolute maximum ratings are those values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.							
<b>Note 2:</b> ESD testing conforms to MIL-STD-883, Method 3015.							
<b>Military Version</b>							
<b>DC Electrical Characteristics</b>							
$V_{EE} = -4.2V$ to $-5.7V$ , $V_{CC} = V_{CCA} = GND$ , $T_C = -55^\circ C$ to $+125^\circ C$							
Symbol	Parameter	Min	Max	Units	$T_C$	Conditions	Notes
$V_{OH}$	Output HIGH Voltage	-1025	-870	mV	0°C to +125°C	$V_{IN} = V_{IH}$ (Max) or $V_{IL}$ (Min)	(Notes 3, 4, 5)
		-1085	-870	mV	-55°C		
$V_{OL}$	Output LOW Voltage	-1830	-1620	mV	0°C to +125°C	$V_{IN} = V_{IH}$ (Min) or $V_{IL}$ (Max)	(Notes 3, 4, 5)
		-1830	-1555	mV	-55°C		
$V_{OHC}$	Output HIGH Voltage	-1035		mV	0°C to +125°C	$V_{IN} = V_{IH}$ (Min) or $V_{IL}$ (Max)	(Notes 3, 4, 5)
		-1085		mV	-55°C		
$V_{OLC}$	Output LOW Voltage		-1610	mV	0°C to +125°C	$V_{IN} = V_{IH}$ (Min) or $V_{IL}$ (Max)	(Notes 3, 4, 5)
			-1555	mV	-55°C		
$V_{IH}$	Input HIGH Voltage	-1165	-870	mV	-55°C to +125°C	Guaranteed HIGH Signal for All Inputs	(Notes 3, 4, 5, 6)
$V_{IL}$	Input LOW Voltage	-1830	-1475	mV	-55°C to +125°C	Guaranteed LOW Signal for All Inputs	(Notes 3, 4, 5, 6)
$I_{IL}$	Input LOW Current	0.50		µA	-55°C to +125°C	$V_{EE} = -4.2V$ $V_{IN} = V_{IL}$ (Min)	(Notes 3, 4, 5)
$I_{IH}$	Input HIGH Current CP, MR $D_0-D_5$		350	µA	0°C to +125°C	$V_{EE} = -5.7V$ $V_{IN} = V_{IH}$ (Max)	(Notes 3, 4, 5)
			240	µA	-55°C		
$I_{EE}$	Power Supply Current		500	µA	-55°C to +125°C	Inputs Open	(Notes 3, 4, 5)
			340	µA	-55°C		
<b>Note 3:</b>	F100K 300 Series cold temperature testing is performed by temperature soaking (to guarantee junction temperature equals $-55^\circ C$ ), then testing immediately without allowing for the junction temperature to stabilize due to heat dissipation after power-up. This provides "cold start" specs which can be considered a worst case condition at cold temperatures.						
<b>Note 4:</b>	Screen tested 100% on each device at $-55^\circ C$ , $+25^\circ C$ , and $+125^\circ C$ , Subgroups 1, 2, 3, 7, and 8.						
<b>Note 5:</b>	Sample tested (Method 5005, Table I) on each manufactured lot at $-55^\circ C$ , $+25^\circ C$ , and $+125^\circ C$ , Subgroups A1, 2, 3, 7, and 8.						
<b>Note 6:</b>	Guaranteed by applying specified input condition and testing $V_{OH}/V_{OL}$ .						

## AC Electrical Characteristics

$V_{EE} = -4.2V$  to  $-5.7V$ ,  $V_{CC} = V_{CCA} = GND$

Symbol	Parameter	$T_C = -55^\circ C$		$T_C = +25^\circ C$		$T_C = +125^\circ C$		Units	Conditions	Notes
		Min	Max	Min	Max	Min	Max			
$f_{max}$	Toggle Frequency	375		375		375		MHz	<i>Figures 2, 3</i>	(Note 10)
$t_{PLH}$	Propagation Delay $CP_a$ , $CP_b$ to Output	0.40	2.40	0.50	2.20	0.50	2.60	ns	<i>Figures 1, 3</i>	(Notes 7, 8, 9)
$t_{PLH}$	Propagation Delay MR to Output	0.60	2.70	0.70	2.60	0.80	2.90	ns	<i>Figures 1, 4</i>	
$t_{TLH}$ $t_{THL}$	Transition Time 20% to 80%, 80% to 20%	0.20	1.60	0.20	1.60	0.20	1.60	ns	<i>Figures 1, 3</i>	(Note 10)
$t_s$	Setup Time $D_0-D_5$ MR (Release Time)	0.90		0.80		0.90		ns	<i>Figure 5</i>	
$t_h$	Hold Time $D_0-D_5$	1.50		1.40		1.60		ns	<i>Figure 5</i>	
$t_{pw(H)}$	Pulse Width HIGH $CP_a$ , $CP_b$ , MR	2.00		2.00		2.00		ns	<i>Figures 3, 4</i>	

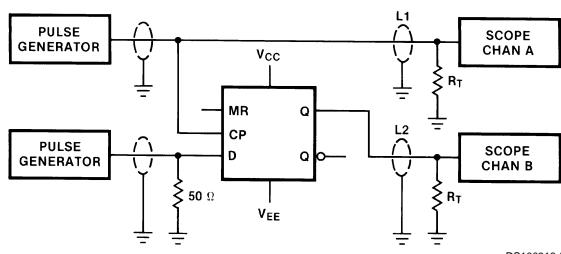
**Note 7:** F100K 300 Series cold temperature testing is performed by temperature soaking (to guarantee junction temperature equals  $-55^\circ C$ ), then testing immediately without allowing for the junction temperature to stabilize due to heat dissipation after power-up. This provides "cold start" specs which can be considered a worst case condition at cold temperatures.

**Note 8:** Screen tested 100% on each device at  $+25^\circ C$ , Temperature only, Subgroup A9.

**Note 9:** Sample tested (Method 5005, Table I) on each Mfg. lot at  $+25^\circ C$ , Subgroup A9, and at  $+125^\circ C$ , and  $-55^\circ C$  Temperature, Subgroups A10 and A11.

**Note 10:** Not tested at  $+25^\circ C$ ,  $+125^\circ C$  and  $-55^\circ C$  Temperature (design characterization data).

## Test Circuitry



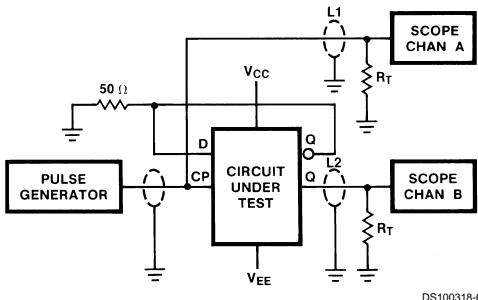
DS100318-5

### Notes:

- $V_{CC}, V_{CCA} = +2V$ ,  $V_{EE} = -2.5V$
- L1 and L2 = equal length  $50\Omega$  impedance lines
- $R_T = 50\Omega$  terminator internal to scope
- Decoupling  $0.1 \mu F$  from GND to  $V_{CC}$  and  $V_{EE}$
- All unused outputs are loaded with  $50\Omega$  to GND
- $C_L$  = Fixture and stray capacitance  $\leq 3 \text{ pF}$

FIGURE 1. AC Test Circuit

## Test Circuitry (Continued)



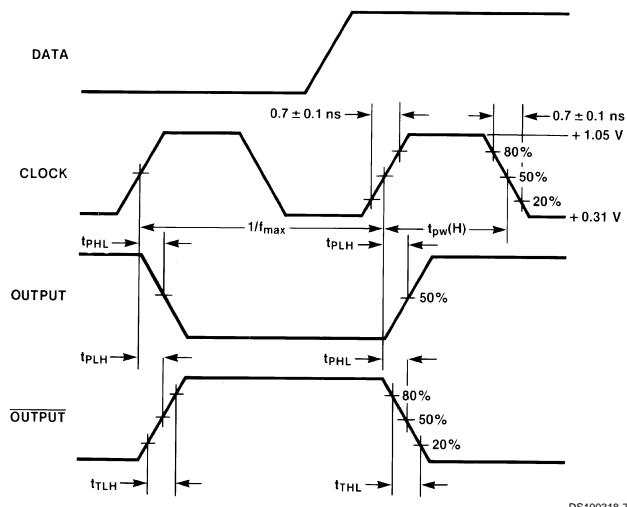
DS100318-6

### Notes:

- V<sub>CC</sub>, V<sub>CCA</sub> = +2V, V<sub>EE</sub> = -2.5V
- L1 and L2 = equal length 50Ω impedance lines
- R<sub>T</sub> = 50Ω terminator internal to scope
- Decoupling 0.1 μF from GND to V<sub>CC</sub> and V<sub>EE</sub>
- All unused outputs are loaded with 50Ω to GND
- C<sub>L</sub> = Jig and stray capacitance ≤ 3 pF

FIGURE 2. Toggle Frequency Test Circuit

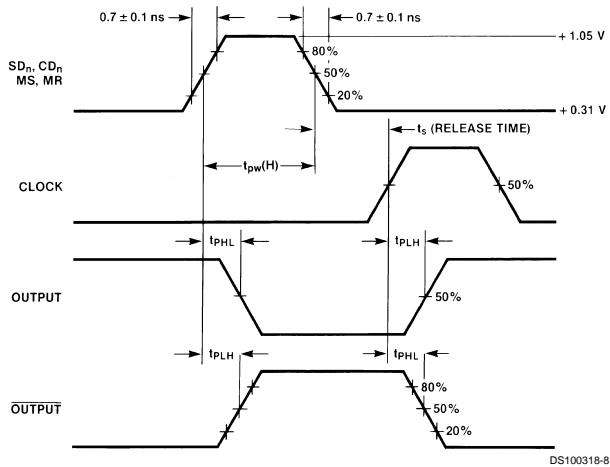
## Switching Waveforms



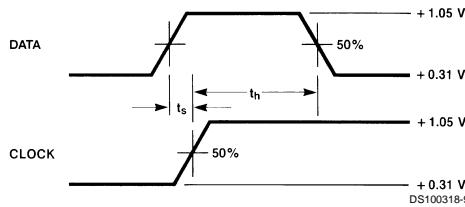
DS100318-7

FIGURE 3. Propagation Delay (Clock) and Transition Times

## Switching Waveforms (Continued)



**FIGURE 4. Propagation Delay (Reset)**



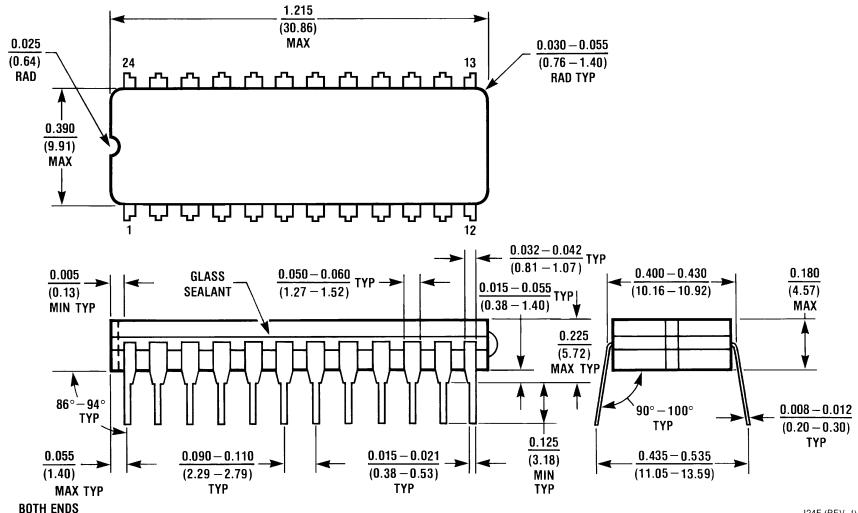
**Notes:**

$t_s$  is the minimum time before the transition of the clock that information must be present at the data input.  
 $t_h$  is the minimum time after the transition of the clock that information must remain unchanged at the data input.

**FIGURE 5. Setup and Hold Time**

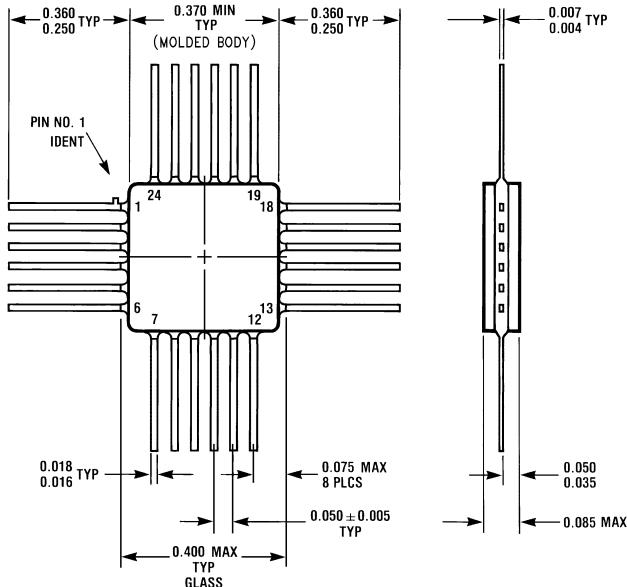
## Physical Dimensions

inches (millimeters) unless otherwise noted



J24E (REV J)

**24-Lead Ceramic Dual-In-Line Package (0.400" Wide) (D)**  
NS Package Number J24E



W24B (REV D)

**24-Lead Quad Cerpak (F)**  
NS Package Number W24B

# 100351 Low Power Hex D Flip-Flop

## LIFE SUPPORT POLICY

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